

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

1. (Currently Amended) A method of distributing power in a semiconductor ~~device~~die, comprising;

providing at least one pair of bond pads to the semiconductor ~~device~~die;

providing an input/output bond pad to the semiconductor ~~device~~die, the input/output bond pad to receive ~~and~~an input/output bond wire operable for electrically connecting to a package;

connecting a single corresponding bond wire between each of the at least one pair of bond pads such that each bond pad of each of the at least one pair of bond pads has only one bond wire end connected thereto; and

locating a first bond pad of the at least one pair of bond pads in an internal portion of the semiconductor die.

2. (Currently Amended) The method of Claim 1 further comprising locating a second bond pad of the at least one pair of bond pads along a periphery of the semiconductor die.

3. (Previously Presented) The method of Claim 1 wherein the single corresponding bond wire comprises a metallic material selected from the group consisting of gold, aluminum, and copper.

4. (Previously Presented) The method of Claim 1 further comprising bonding the single corresponding bond wire to the pair of bond pads using a wire bond type selected from the group consisting of ball bonds, stitch bonds, stitch bonds on bonding pad, and stitch bonds on ball.

5. (Previously Presented) The method of Claim 1 further comprising connecting a trace in the semiconductor die between bond pads of the pair of bond pads.

6. (Previously Presented) The method of Claim 1 further comprising locating a second bond pad of the at least one pair of bond pads in the internal portion of the semiconductor die.

7. (Previously Presented) The method of Claim 1 wherein the single corresponding bond wire is selected from the group consisting of power interconnects, ground interconnects, and signal interconnects.

8. (Previously Presented) The method of Claim 1 further comprising: attaching a plurality of pairs of bond pads to the semiconductor die; and

connecting a corresponding wire between each of the pairs of bond pads such that each bond pad of the pairs of bond pads includes a single wire bond.

9. (New) The method of Claim 1 further comprising locating the input/output bond pad on a first bond surface and a second bond pad of the at least one pair of bond pads on the first bond surface.